

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Suan J. Boon

Title: METHOD OF PACKAGING AT A WAFER LEVEL

Docket No.: 303.601US3

Serial No.: 10/722,838

Filed: November 26, 2003

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Examiner: James M. Mitchell

Group Art Unit: 2813

MS AF

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

X Amendment and Response under 37 CFR 1.116 (11 pgs.).

Please consider this a **PETITION FOR EXTENSION OF TIME** for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG & WOESSNER, P.A.

Customer Number 21186

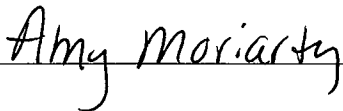
By: 

Atty: David R. Cochran

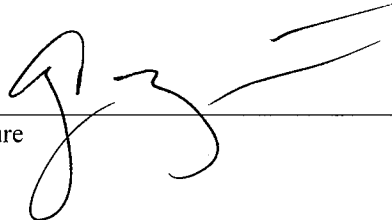
Reg. No. 46,632

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being filed using the USPTO's electronic filing system EFS-Web, and is addressed to: MS AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 7th day of March, 2008.

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